IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1					Form Type Distribute						eous Materia	ials and Mfg Information			
Supplier	Information														
Company	name*	Company unique ID			τ	Unique ID Authority					Response Date*				
On Semice	onductor											2021-02-03			
Contact N	ame		Title - Contact			I	Phone - Contact*					Email - Contact*			
Product-I	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorize	d Representative*		Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item	Number Mfr Item Name				Effective Da	Date Version Manufacturing Site		ring Site	1	Veight*	UOM	Unit Type	
		FDD10N20LZTM		UF 200V 360mOhm L DPAK			2021-02-03			СРА		2	91.831	mg	Each
Manufa	cturing Proccess Informat	tion													,
	Terminal Plating / Grid Array Ma	Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Tempera		ture Max Time at Peak Tempe		Temperat	ire Nui	mber of Reflow	Cycles			
	Matte Tin (Sn) - annealed		CU Alloy 1			260	0 C		30		secon	is 3			
Comments															
evel 1 - m	aximum time at peak temperatu	re during sol	dering is 10-3	0 seconds											
or more	information regarding material	composition <b>j</b>	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.93	mg	Supplier	Silicon (Si)	7440-21-3		5.93	mg
Die Attach Solder	2.353	mg	Supplier	Silver (Ag)	7440-22-4		0.0588	mg
			A	Lead (Pb)	7439-92-1	7a	2.1765	mg
			Supplier	Tin (Sn)	7440-31-5		0.1176	mg
Lead Frame	150.208		Supplier	Tin (Sn)	7440-31-5		0.16	mg
			В	Nickel (Ni)	7440-02-0		0.048	mg
			Supplier	Copper (Cu)	7440-50-8		150	mg
Mold Compound-Black	129.0		Supplier	Ortho Cresol Novolac Resin	29690-82-2		25.8	mg
			Supplier	Carbon Black (C)	1333-86-4		1.29	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		101.91	mg
Plating	1.9	mg	Supplier	Tin (Sn)	7440-31-5		1.9	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg